



PMBFJ174; PMBFJ175; PMBFJ176; PMBFJ177

P-channel silicon field-effect transistors

Rev. 3.0 — 24 January 2020

Product data sheet

1 Product profile

1.1 General description

Silicon symmetrical p-channel junction FETs in plastic microminiature SOT23 envelopes. They are intended for application with analogue switches, choppers, commutators etc. using SMD technology. A special feature is the interchangeability of the drain and source connections.

1.2 Quick reference data

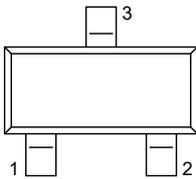
Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{DS}	drain-source voltage		30	-	30	V
V_{GS0}	gate-source voltage		-	-	30	V
$-I_G$	gate current		-	-	50	mA
P_{tot}	total power dissipation	up to $T_{amb} = 25^\circ\text{C}$	-	-	300	mW
$-I_{DSS}$	drain current	$-V_{DS} = 15\text{ V}; V_{GS} = 0$				
		PMBFJ174	20	-	135	mA
		PMBFJ175	7	-	70	mA
		PMBFJ176	2	-	35	mA
	PMBFJ177	1.5	-	20	mA	
$R_{DS\ on}$	drain-source ON-resistance	$-V_{DS} = 0.1\text{ V}; V_{GS} = 0$				
		PMBFJ174	-	-	85	Ω
		PMBFJ175	-	-	125	Ω
		PMBFJ176	-	-	250	Ω
	PMBFJ177	-	-	300	Ω	



2 Pinning information

Table 2. Pinning

Pin	Description ^[1]		Simplified outline	Symbol
1	drain			 sym053
2	source			
3	gate			

[1] Drain and source are interchangeable.

3 Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PMBFJ174	-	plastic surface mounted package; 3 leads	SOT23
PMBFJ175			
PMBFJ176			
PMBFJ177			

4 Marking

Table 4. Marking

Type number	Marking code ^[1]
PMBFJ174	*6X
PMBFJ175	*6W
PMBFJ176	*6S
PMBFJ177	*6Y

[1] * = manufacturing site

5 Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DS}	drain-source voltage		30	30	V
V_{GSO}	gate-source voltage		-	30	V
V_{GDO}	gate-drain voltage		-	30	V

Symbol	Parameter	Conditions	Min	Max	Unit
$-I_G$	gate current (DC)		-	50	mA
P_{tot}	total power dissipation	$T_{amb} = 25\text{ °C}$	[1]	300	mW
T_{stg}	storage temperature range		-65	150	°C
T_j	junction temperature		-	150	°C

[1] Mounted on a ceramic substrate, 8 mm × 10 mm × 0.7 mm.

6 Thermal characteristics

Table 6. Thermal characteristics

$$T_j = P (R_{th(j-t)} + R_{th(t-s)} + R_{th(s-a)}) + T_{amb}$$

Symbol	Parameter	Conditions	Typ	Unit
$R_{th(j-a)}$	junction to ambient in free air thermal resistance		430	K/W

7 Static characteristics

Table 7. Static characteristics

$T_j = 25\text{ °C}$ unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
I_{GSS}	gate cut-off current					
	PMBFJ174	$V_{GS} = 20\text{ V}; V_{DS} = 0\text{ V}$	-	-	1	nA
	PMBFJ175	$V_{GS} = 20\text{ V}; V_{DS} = 0\text{ V}$	-	-	1	nA
	PMBFJ176	$V_{GS} = 20\text{ V}; V_{DS} = 0\text{ V}$	-	-	1	nA
$-I_{DSX}$	drain cut-off current					
	PMBFJ174	$-V_{DS} = 15\text{ V}; V_{GS} = 10\text{ V}$	-	-	1	nA
	PMBFJ175	$-V_{DS} = 15\text{ V}; V_{GS} = 10\text{ V}$	-	-	1	nA
	PMBFJ176	$-V_{DS} = 15\text{ V}; V_{GS} = 10\text{ V}$	-	-	1	nA
$-I_{DSS}$	drain current					
	PMBFJ174	$V_{DS} = -15\text{ V}; V_{GS} = 0\text{ V}$	20	-	135	mA
	PMBFJ175	$-V_{DS} = 15\text{ V}; V_{GS} = 0\text{ V}$	7	-	70	mA
	PMBFJ176	$-V_{DS} = 15\text{ V}; V_{GS} = 0\text{ V}$	2	-	35	mA
$V_{(BR)GSS}$	gate-source breakdown voltage					
	PMBFJ174	$I_G = 1\text{ }\mu\text{A}; V_{DS} = 0\text{ V}$	-	-	30	V
	PMBFJ175	$I_G = 1\text{ }\mu\text{A}; V_{DS} = 0\text{ V}$	-	-	30	V
	PMBFJ176	$I_G = 1\text{ }\mu\text{A}; V_{DS} = 0\text{ V}$	-	-	30	V
	PMBFJ177	$I_G = 1\text{ }\mu\text{A}; V_{DS} = 0\text{ V}$	-	-	30	V

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V _{GSoff}	gate-source cut-off voltage					
	PMBFJ174	-I _D = 10 nA; V _{DS} = -15 V	5	-	10	V
	PMBFJ175	-I _D = 10 nA; V _{DS} = -15 V	3	-	6	V
	PMBFJ176	-I _D = 10 nA; V _{DS} = -15 V	1	-	4	V
R _{DSon}	drain-source on resistance					
	PMBFJ174	-V _{DS} = 0.1 V; V _{GS} = 0 V	-	-	85	Ω
	PMBFJ175	-V _{DS} = 0.1 V; V _{GS} = 0 V	-	-	125	Ω
	PMBFJ176	-V _{DS} = 0.1 V; V _{GS} = 0 V	-	-	250	Ω
PMBFJ177	-V _{DS} = 0.1 V; V _{GS} = 0 V		-	-	300	Ω

8 Dynamic characteristics

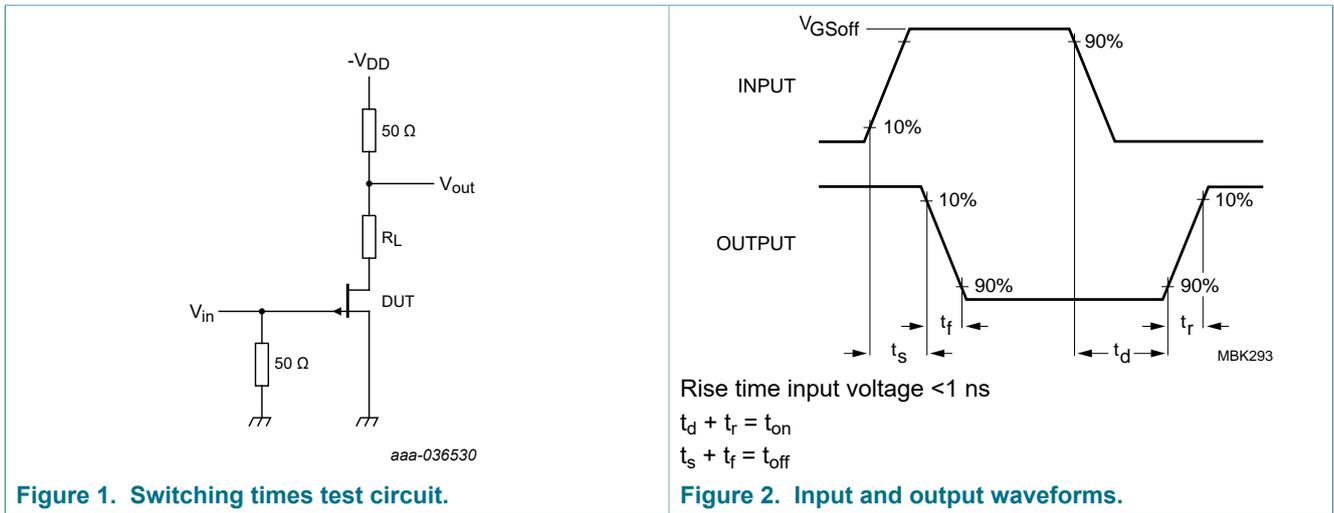
Table 8. Dynamic characteristics

T_j = 25 °C unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
C _{iss}	input capacitance	V _{GS} = 10 V; V _{DS} = 0 V; f = 1 MHz	-	8	-	pF	
		V _{DS} = 0 V; V _{GS} = 0 V; f = 1 MHz	-	30	-	pF	
C _{rs}	feedback capacitance	V _{GS} = 10 V; V _{DS} = 0 V; f = 1 MHz	-	4	-	pF	
Switching times; see Figure 1 and Figure 2. Test conditions for switching times are as follows: ^[1]							
t _d	delay time						
	PMBFJ174		-	2	-	ns	
	PMBFJ175		-	5	-	ns	
	PMBFJ176		-	15	-	ns	
PMBFJ177	-		-	20	-	ns	
	t _r	rise time					
		PMBFJ174		-	5	-	ns
		PMBFJ175		-	10	-	ns
PMBFJ176			-	20	-	ns	
PMBFJ177	-		-	25	-	ns	
	t _{on}	turn-on time					
		PMBFJ174		-	7	-	ns
		PMBFJ175		-	15	-	ns
PMBFJ176			-	35	-	ns	
PMBFJ177	-		-	45	-	ns	

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
t _s	storage temperature					
	PMBFJ174		-	5	-	ns
	PMBFJ175		-	10	-	ns
	PMBFJ176		-	15	-	ns
t _f	fall time					
	PMBFJ174		-	10	-	ns
	PMBFJ175		-	20	-	ns
	PMBFJ176		-	20	-	ns
t _{off}	turn-off time					
	PMBFJ174		-	6	-	ns
	PMBFJ175		-	6	-	ns
	PMBFJ176		-	6	-	ns
t _{off}	turn-off time					
	PMBFJ174		-	6	-	ns
	PMBFJ175		-	6	-	ns
	PMBFJ176		-	6	-	ns

- [1] -V_{DD} = 10 V, V_{GSoff} = 12 V, R_L = 560 Ω, V_{GSon} = 0 V (PMBFJ174);
- V_{DD} = 6 V, V_{GSoff} = 8 V, R_L = 1200 Ω, V_{GSon} = 0 V (PMBFJ175);
- V_{DD} = 6 V, V_{GSoff} = 6 V, R_L = 2000 Ω, V_{GSon} = 0 V (PMBFJ176);
- V_{DD} = 6 V, V_{GSoff} = 3 V, R_L = 2900 Ω, V_{GSon} = 0 V (PMBFJ177);



9 Package outline

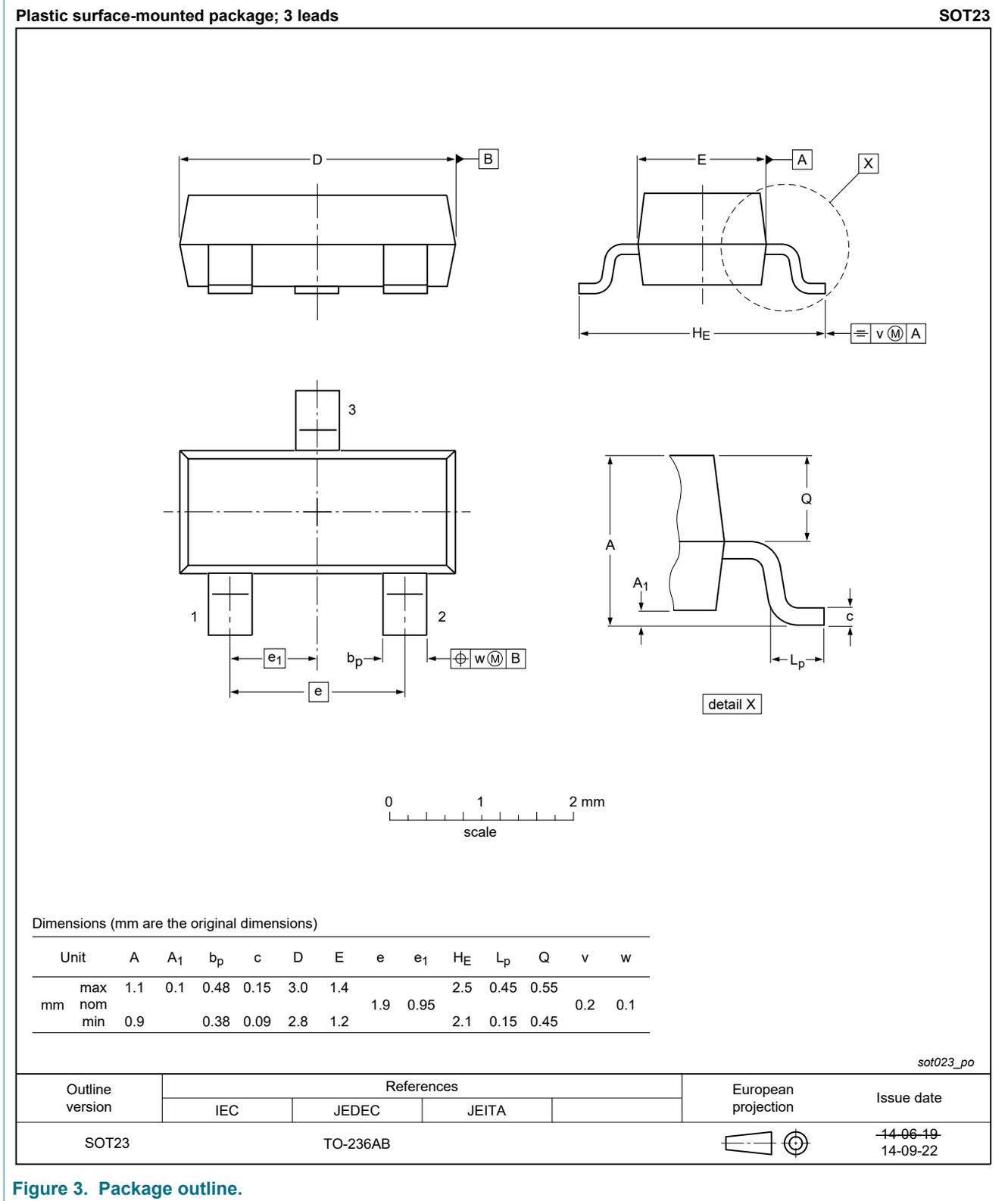


Figure 3. Package outline.

10 Revision history

Revision history

Revision number	Date	Description
3.0	20200124	Product data sheet
modification		• adapted the notation of the manufacturing code
2.0	19950401	product data sheet
1.0		Initial version of the document

11 Legal information

11.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

11.2 Definitions

Draft — The document is a draft version only. The content is still under internal review and subject to formal approval, which may result in modifications or additions. NXP Semiconductors does not give any representations or warranties as to the accuracy or completeness of information included herein and shall have no liability for the consequences of use of such information.

Short data sheet — A short data sheet is an extract from a full data sheet with the same product type number(s) and title. A short data sheet is intended for quick reference only and should not be relied upon to contain detailed and full information. For detailed and full information see the relevant full data sheet, which is available on request via the local NXP Semiconductors sales office. In case of any inconsistency or conflict with the short data sheet, the full data sheet shall prevail.

Product specification — The information and data provided in a Product data sheet shall define the specification of the product as agreed between NXP Semiconductors and its customer, unless NXP Semiconductors and customer have explicitly agreed otherwise in writing. In no event however, shall an agreement be valid in which the NXP Semiconductors product is deemed to offer functions and qualities beyond those described in the Product data sheet.

11.3 Disclaimers

Limited warranty and liability — Information in this document is believed to be accurate and reliable. However, NXP Semiconductors does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. NXP Semiconductors takes no responsibility for the content in this document if provided by an information source outside of NXP Semiconductors. In no event shall NXP Semiconductors be liable for any indirect, incidental, punitive, special or consequential damages (including - without limitation - lost profits, lost savings, business interruption, costs related to the removal or replacement of any products or rework charges) whether or not such damages are based on tort (including negligence), warranty, breach of contract or any other legal theory. Notwithstanding any damages that customer might incur for any reason whatsoever, NXP Semiconductors' aggregate and cumulative liability towards customer for the products described herein shall be limited in accordance with the Terms and conditions of commercial sale of NXP Semiconductors.

Right to make changes — NXP Semiconductors reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without

notice. This document supersedes and replaces all information supplied prior to the publication hereof.

Suitability for use — NXP Semiconductors products are not designed, authorized or warranted to be suitable for use in life support, life-critical or safety-critical systems or equipment, nor in applications where failure or malfunction of an NXP Semiconductors product can reasonably be expected to result in personal injury, death or severe property or environmental damage. NXP Semiconductors and its suppliers accept no liability for inclusion and/or use of NXP Semiconductors products in such equipment or applications and therefore such inclusion and/or use is at the customer's own risk.

Applications — Applications that are described herein for any of these products are for illustrative purposes only. NXP Semiconductors makes no representation or warranty that such applications will be suitable for the specified use without further testing or modification. Customers are responsible for the design and operation of their applications and products using NXP Semiconductors products, and NXP Semiconductors accepts no liability for any assistance with applications or customer product design. It is customer's sole responsibility to determine whether the NXP Semiconductors product is suitable and fit for the customer's applications and products planned, as well as for the planned application and use of customer's third party customer(s). Customers should provide appropriate design and operating safeguards to minimize the risks associated with their applications and products. NXP Semiconductors does not accept any liability related to any default, damage, costs or problem which is based on any weakness or default in the customer's applications or products, or the application or use by customer's third party customer(s). Customer is responsible for doing all necessary testing for the customer's applications and products using NXP Semiconductors products in order to avoid a default of the applications and the products or of the application or use by customer's third party customer(s). NXP does not accept any liability in this respect.

Limiting values — Stress above one or more limiting values (as defined in the Absolute Maximum Ratings System of IEC 60134) will cause permanent damage to the device. Limiting values are stress ratings only and (proper) operation of the device at these or any other conditions above those given in the Recommended operating conditions section (if present) or the Characteristics sections of this document is not warranted. Constant or repeated exposure to limiting values will permanently and irreversibly affect the quality and reliability of the device.

Terms and conditions of commercial sale — NXP Semiconductors products are sold subject to the general terms and conditions of commercial sale, as published at <http://www.nxp.com/profile/terms>, unless otherwise agreed in a valid written individual agreement. In case an individual agreement is concluded only the terms and conditions of the respective agreement shall apply. NXP Semiconductors hereby expressly objects to applying the customer's general terms and conditions with regard to the purchase of NXP Semiconductors products by customer.

No offer to sell or license — Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.

Quick reference data — The Quick reference data is an extract of the product data given in the Limiting values and Characteristics sections of this document, and as such is not complete, exhaustive or legally binding.

Export control — This document as well as the item(s) described herein may be subject to export control regulations. Export might require a prior authorization from competent authorities.

Non-automotive qualified products — Unless this data sheet expressly states that this specific NXP Semiconductors product is automotive qualified, the product is not suitable for automotive use. It is neither qualified nor tested in accordance with automotive testing or application requirements. NXP Semiconductors accepts no liability for inclusion and/or use of non-automotive qualified products in automotive equipment or applications. In the event that customer uses the product for design-in and use in automotive

applications to automotive specifications and standards, customer (a) shall use the product without NXP Semiconductors' warranty of the product for such automotive applications, use and specifications, and (b) whenever customer uses the product for automotive applications beyond NXP Semiconductors' specifications such use shall be solely at customer's own risk, and (c) customer fully indemnifies NXP Semiconductors for any liability, damages or failed product claims resulting from customer design and use of the product for automotive applications beyond NXP Semiconductors' standard warranty and NXP Semiconductors' product specifications.

Translations — A non-English (translated) version of a document is for reference only. The English version shall prevail in case of any discrepancy between the translated and English versions.

11.4 Trademarks

Notice: All referenced brands, product names, service names and trademarks are the property of their respective owners.

Contents

1	Product profile	1
1.1	General description	1
1.2	Quick reference data	1
2	Pinning information	2
3	Ordering information	2
4	Marking	2
5	Limiting values	2
6	Thermal characteristics	3
7	Static characteristics	3
8	Dynamic characteristics	4
9	Package outline	6
10	Revision history	7
11	Legal information	8

Please be aware that important notices concerning this document and the product(s) described herein, have been included in section 'Legal information'.

© NXP B.V. 2020.

All rights reserved.

For more information, please visit: <http://www.nxp.com>

For sales office addresses, please send an email to: salesaddresses@nxp.com

Date of release: 24 January 2020

Document identifier: PMBFJ174_175_176_177